

MC74HC390A

Dual 4-Stage Binary Ripple Counter with $\div 2$ and $\div 5$ Sections

High-Performance Silicon-Gate CMOS

The MC74HC390A is identical in pinout to the LS390. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

This device consists of two independent 4-bit counters, each composed of a divide-by-two and a divide-by-five section. The divide-by-two and divide-by-five counters have separate clock inputs, and can be cascaded to implement various combinations of $\div 2$ and/or $\div 5$ up to a $\div 100$ counter.

Flip-flops internal to the counters are triggered by high-to-low transitions of the clock input. A separate, asynchronous reset is provided for each 4-bit counter. State changes of the Q outputs do not occur simultaneously because of internal ripple delays. Therefore, decoded output signals are subject to decoding spikes and should not be used as clocks or strobes except when gated with the Clock of the HC390A.

Features

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1 μ A
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard No 7 A
- Chip Complexity: 244 FETs or 61 Equivalent Gates
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

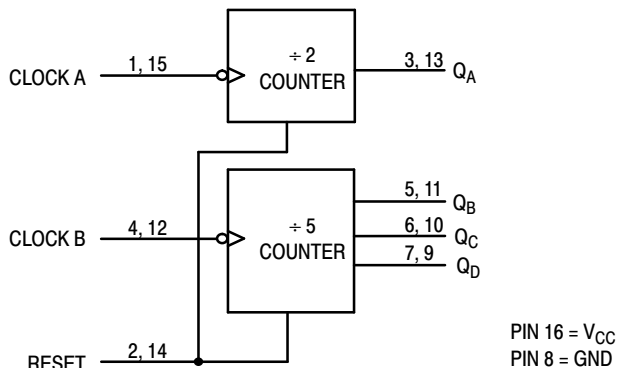
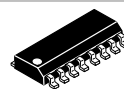


Figure 1. Logic Diagram

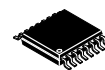


ON Semiconductor®

<http://onsemi.com>

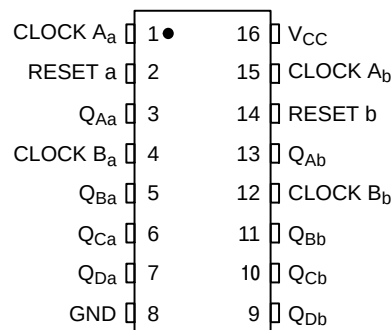


SOIC-16
D SUFFIX
CASE 751B

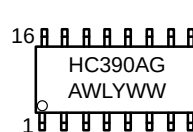


TSSOP-16
DT SUFFIX
CASE 948F

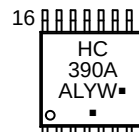
PIN ASSIGNMENT



MARKING DIAGRAMS



SOIC-16



TSSOP-16

A = Assembly Location
L, WL = Wafer Lot
Y, YY = Year
W, WW = Work Week
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

FUNCTION TABLE

Clock		Reset	Action
A	B		
X	X	H	Reset $\div 2$ and $\div 5$
$\sim$	X	L	Increment $\div 2$
X	$\sim$	L	Increment $\div 5$

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

MC74HC390A

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
V_{in}	DC Input Voltage (Referenced to GND)	-0.5 to $V_{CC} + 0.5$	V
V_{out}	DC Output Voltage (Referenced to GND)	-0.5 to $V_{CC} + 0.5$	V
I_{in}	DC Input Current, per Pin	± 20	mA
I_{out}	DC Output Current, per Pin	± 25	mA
I_{CC}	DC Supply Current, V_{CC} and GND Pins	± 50	mA
P_D	Power Dissipation in Still Air, SOIC Package† TSSOP Package†	500 450	mW
T_{stg}	Storage Temperature	-65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 Seconds SOIC or TSSOP Package	260	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $GND \leq (V_{in} \text{ or } V_{out}) \leq V_{CC}$. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

†Derating: SOIC Package: -7 mW/°C from 65° to 125°C

TSSOP Package: -6.1 mW/°C from 65° to 125°C

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	DC Supply Voltage (Referenced to GND)	2.0	6.0	V
V _{in} , V _{out}	DC Input Voltage, Output Voltage (Referenced to GND)	0	V _{CC}	V
T _A	Operating Temperature, All Package Types	−55	+125	°C
t _r , t _f	Input Rise and Fall Time (Figure 1) V_{CC} = 2.0 V V_{CC} = 3.0 V V_{CC} = 4.5 V V_{CC} = 6.0 V	0 0 0 0	1000 600 500 400	ns

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	V_{CC} V	Guaranteed Limit			Unit
				-55 to 25°C	≤ 85°C	≤ 125°C	
V_{IH}	Minimum High-Level Input Voltage	$V_{out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out} \leq 20 \mu\text{A}$	2.0 3.0 4.5 6.0	1.5 2.1 3.15 4.2	1.5 2.1 3.15 4.2	1.5 2.1 3.15 4.2	V
V_{IL}	Maximum Low-Level Input Voltage	$V_{out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out} \leq 20 \mu\text{A}$	2.0 3.0 4.5 6.0	0.5 0.9 1.35 1.8	0.5 0.9 1.35 1.8	0.5 0.9 1.35 1.8	V
V_{OH}	Minimum High-Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out} \leq 20 \mu\text{A}$	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out} \leq 2.4 \text{ mA}$	3.0	2.48	2.34	2.20	
		$ I_{out} \leq 4.0 \text{ mA}$	4.5	3.98	3.84	3.70	
		$ I_{out} \leq 5.2 \text{ mA}$	6.0	5.48	5.34	5.20	
V_{OL}	Maximum Low-Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out} \leq 20 \mu\text{A}$	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out} \leq 2.4 \text{ mA}$	3.0	0.26	0.33	0.40	
		$ I_{out} \leq 4.0 \text{ mA}$	4.5	0.26	0.33	0.40	
		$ I_{out} \leq 5.2 \text{ mA}$	6.0	0.26	0.33	0.40	

MC74HC390A

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND) (continued)

Symbol	Parameter	Test Conditions	V _{CC} V	Guaranteed Limit			Unit
				-55 to 25°C	≤ 85°C	≤ 125°C	
I _{in}	Maximum Input Leakage Current	V _{in} = V _{CC} or GND	6.0	±0.1	±1.0	±1.0	μA
I _{CC}	Maximum Quiescent Supply Current (per Package)	V _{in} = V _{CC} or GND I _{out} = 0 μA	6.0	4	40	160	μA

AC ELECTRICAL CHARACTERISTICS (C_L = 50 pF, Input t_f = t_r = 6 ns)

Symbol	Parameter	V _{CC} V	Guaranteed Limit			Unit
			-55 to 25°C	≤ 85°C	≤ 125°C	
f _{max}	Maximum Clock Frequency (50% Duty Cycle) (Figures 1 and 3)	2.0 3.0 4.5 6.0	10 15 30 50	9 14 28 45	8 12 25 40	MHz
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Clock A to QA (Figures 1 and 3)	2.0 3.0 4.5 6.0	70 40 24 20	80 45 30 26	90 50 36 31	ns
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Clock A to QC (QA connected to Clock B) (Figures 1 and 3)	2.0 3.0 4.5 6.0	200 160 58 49	250 185 65 62	300 210 70 68	ns
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Clock B to QB (Figures 1 and 3)	2.0 3.0 4.5 6.0	70 40 26 22	80 45 33 28	90 50 39 33	ns
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Clock B to QC (Figures 1 and 3)	2.0 3.0 4.5 6.0	90 56 37 31	105 70 46 39	180 100 56 48	ns
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Clock B to QD (Figures 1 and 3)	2.0 3.0 4.5 6.0	70 40 26 22	80 45 33 28	90 50 39 33	ns
t _{PHL}	Maximum Propagation Delay, Reset to any Q (Figures 2 and 3)	2.0 3.0 4.5 6.0	80 48 30 26	95 65 38 33	110 75 44 39	ns
t _{TLH} , t _{THL}	Maximum Output Transition Time, Any Output (Figures 1 and 3)	2.0 3.0 4.5 6.0	75 27 15 13	95 32 19 15	110 36 22 19	ns
C _{in}	Maximum Input Capacitance	–	10	10	10	pF

C _{PD}	Power Dissipation Capacitance (Per Counter)*	Typical @ 25°C, V _{CC} = 5.0 V	pF
		35	

* Used to determine the no-load dynamic power consumption: P_D = C_{PD} V_{CC}²f + I_{CC} V_{CC}.

MC74HC390A

TIMING REQUIREMENTS (Input $t_r = t_f = 6$ ns)

Symbol	Parameter	V _{CC} V	Guaranteed Limit			Unit
			-55 to 25°C	≤ 85°C	≤ 125°C	
t_{rec}	Minimum Recovery Time, Reset Inactive to Clock A or Clock B (Figure 3)	2.0	25	30	40	ns
		3.0	15	20	30	
		4.5	10	13	15	
		6.0	9	11	13	
t_w	Minimum Pulse Width, Clock A, Clock B (Figure 2)	2.0	75	95	110	ns
		3.0	27	32	36	
		4.5	15	19	22	
		6.0	13	15	19	
t_w	Minimum Pulse Width, Reset (Figure 3)	2.0	75	95	110	ns
		3.0	27	32	36	
		4.5	20	24	30	
		6.0	18	22	28	
t_r, t_f	Maximum Input Rise and Fall Times (Figure 2)	2.0	1000	1000	1000	ns
		3.0	800	800	800	
		4.5	500	500	500	
		6.0	400	400	400	

PIN DESCRIPTIONS

INPUTS

Clock A (Pins 1, 15) and Clock B (Pins 4, 15)

Clock A is the clock input to the ÷ 2 counter; Clock B is the clock input to the ÷ 5 counter. The internal flip-flops are toggled by high-to-low transitions of the clock input.

CONTROL INPUTS

Reset (Pins 2, 14)

Asynchronous reset. A high at the Reset input prevents counting, resets the internal flip-flops, and forces Q_A through Q_D low.

OUTPUTS

Q_A (Pins 3, 13)

Output of the ÷ 2 counter.

Q_B, Q_C, Q_D (Pins 5, 6, 7, 9, 10, 11)

Outputs of the ÷ 5 counter. Q_D is the most significant bit. Q_A is the least significant bit when the counter is connected for BCD output as in Figure 5. Q_B is the least significant bit when the counter is operating in the bi-quinary mode as in Figure 6.

SWITCHING WAVEFORMS

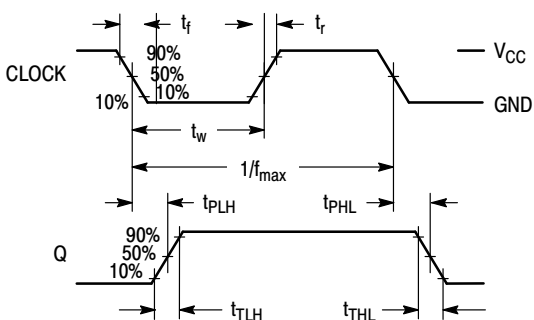


Figure 2.

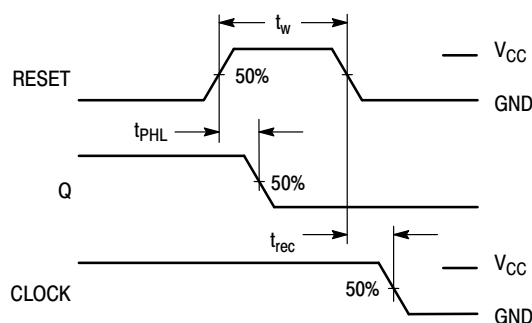
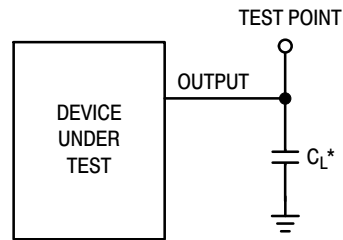


Figure 3.

MC74HC390A

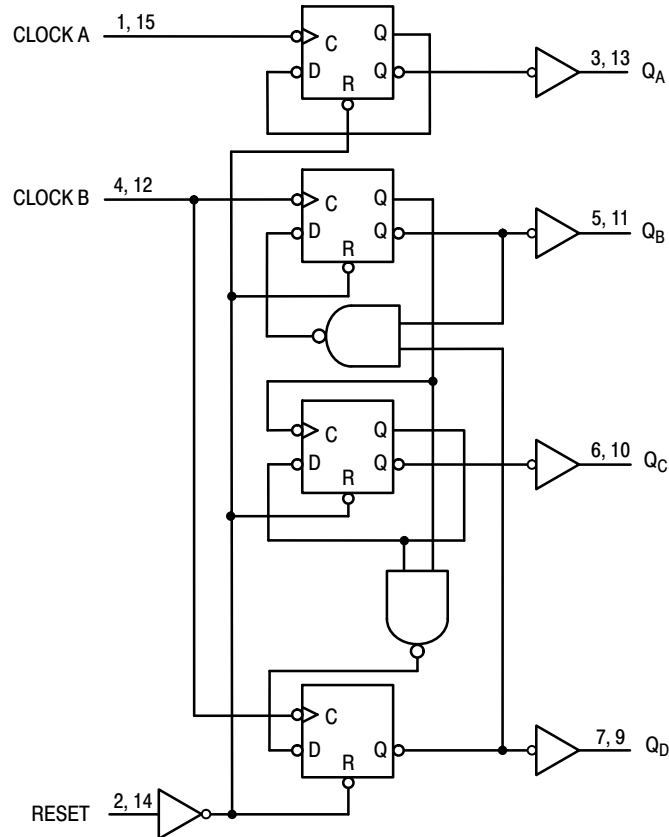
TEST CIRCUIT



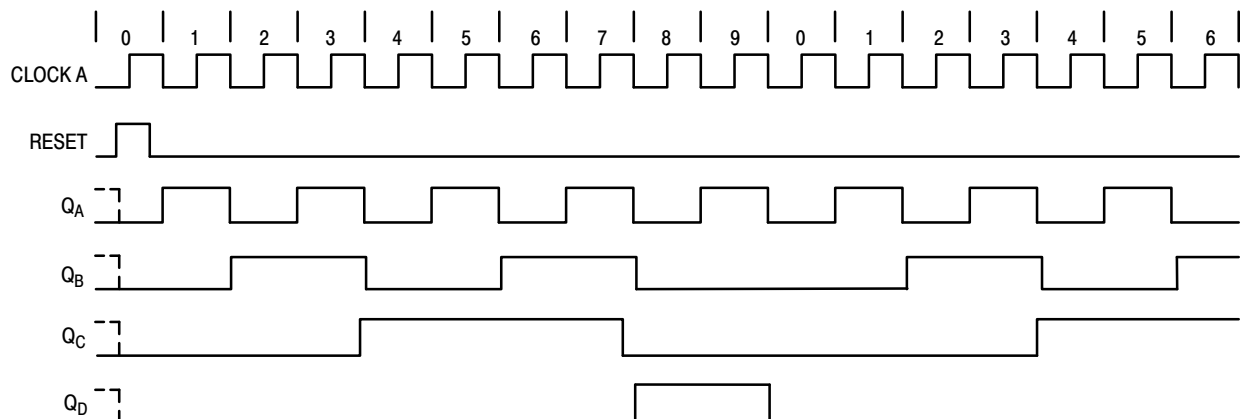
*Includes all probe and jig capacitance

Figure 4.

EXPANDED LOGIC DIAGRAM



TIMING DIAGRAM (QA Connected to Clock B)



MC74HC390A

APPLICATIONS INFORMATION

Each half of the MC54/74HC390A has independent $\div 2$ and $\div 5$ sections (except for the Reset function). The $\div 2$ and $\div 5$ counters can be connected to give BCD or bi-quinary (2–5) count sequences. If Output Q_A is connected to the Clock B input (Figure 4), a decade divider with BCD output is obtained. The function table for the BCD count sequence is given in Table 1.

Table 1. BCD Count Sequence*

Count	Output			
	Q_D	Q_C	Q_B	Q_A
0	L	L	L	L
1	L	L	L	H
2	L	L	H	L
3	L	L	H	H
4	L	H	L	L
5	L	H	L	H
6	L	H	H	L
7	L	H	H	H
8	H	L	L	L
9	H	L	L	H

* Q_A connected to Clock B input.

To obtain a bi-quinary count sequence, the input signals connected to the Clock B input, and output Q_D is connected to the Clock A input (Figure 6). Q_A provides a 50% duty cycle output. The bi-quinary count sequence function table is given in Table 2.

Table 2. Bi-Quinary Count Sequence**

Count	Output			
	Q_A	Q_D	Q_C	Q_B
0	L	L	L	L
1	L	L	L	H
2	L	L	H	L
3	L	L	H	H
4	L	H	L	L
8	H	L	L	L
9	H	L	L	H
10	H	L	H	L
11	H	L	H	H
12	H	H	L	L

** Q_D connected to Clock A input.

CONNECTION DIAGRAMS

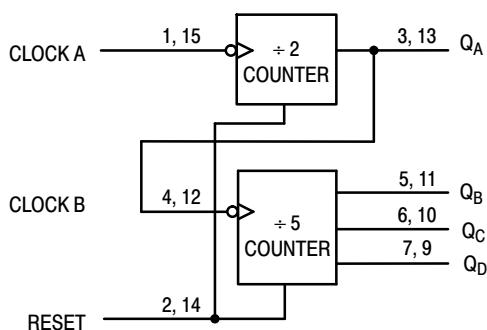


Figure 5. BCD Count

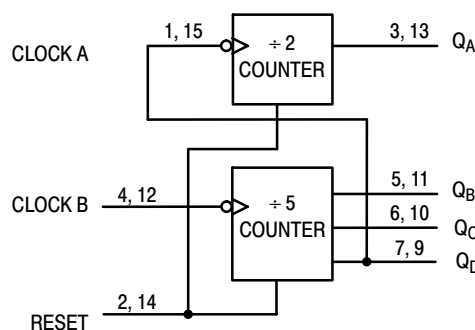


Figure 6. Bi-Quinary Count

ORDERING INFORMATION

Device	Package	Shipping†
MC74HC390ADG	SOIC-16 (Pb-Free)	48 Units / Rail
MC74HC390ADR2G	SOIC-16 (Pb-Free)	2500 / Tape & Reel
MC74HC390ADTR2G	TSSOP-16 (Pb-Free)	2500 / Tape & Reel
NLV74HC390ADR2G*	SOIC-16 (Pb-Free)	2500 / Tape & Reel

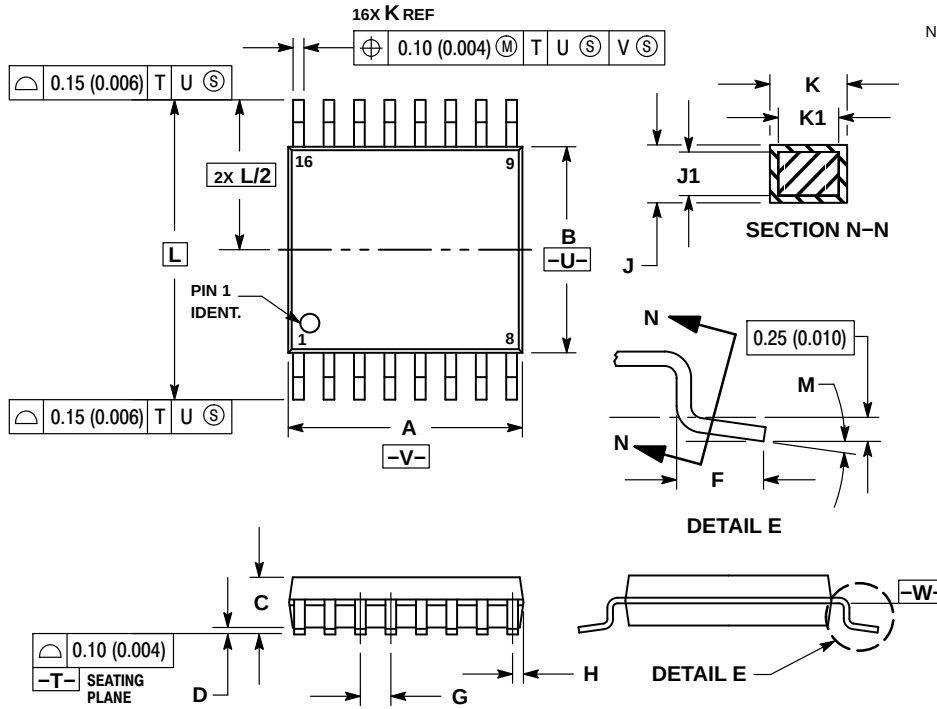
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

MC74HC390A

PACKAGE DIMENSIONS

TSSOP-16
CASE 948F
ISSUE B

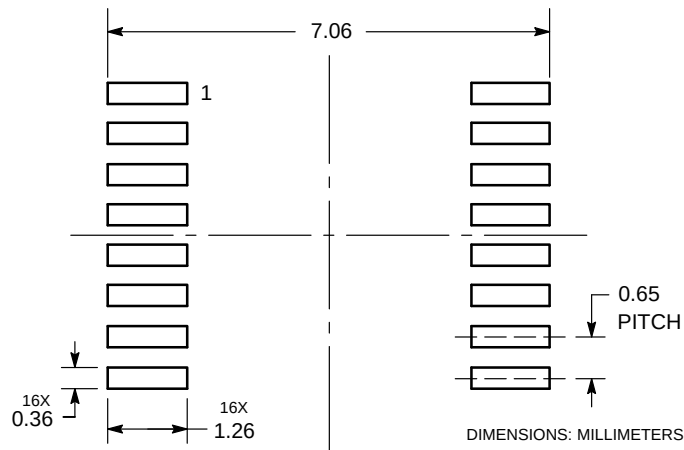


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

SOLDERING FOOTPRINT*

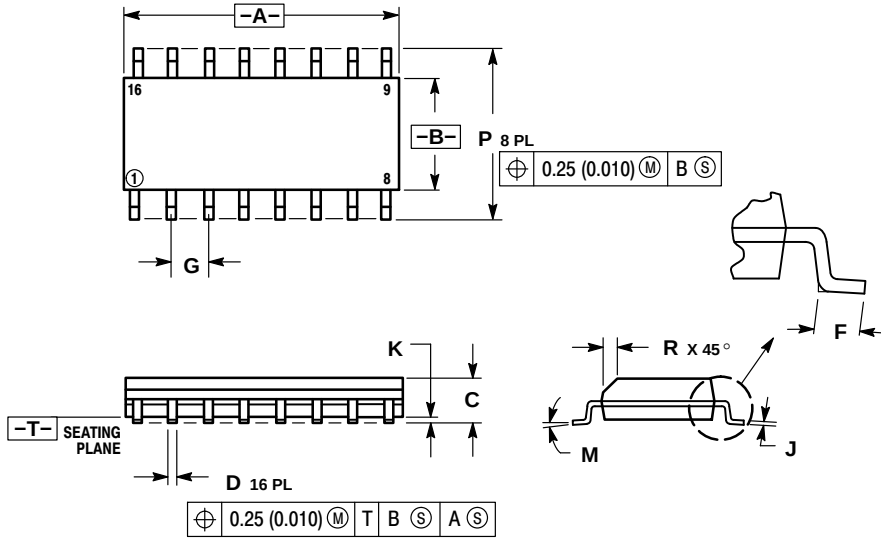


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC74HC390A

PACKAGE DIMENSIONS

SOIC-16
CASE 751B-05
ISSUE K

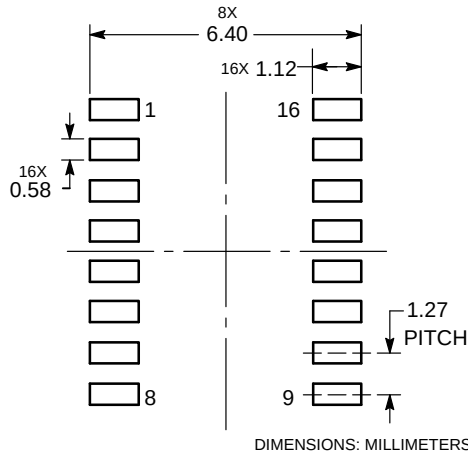


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and the are registered trademarks of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries. SCILLC owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of SCILLC's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marketing.pdf. SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free
USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: <http://www.onsemi.com/orderlit>

For additional information, please contact your local Sales Representative